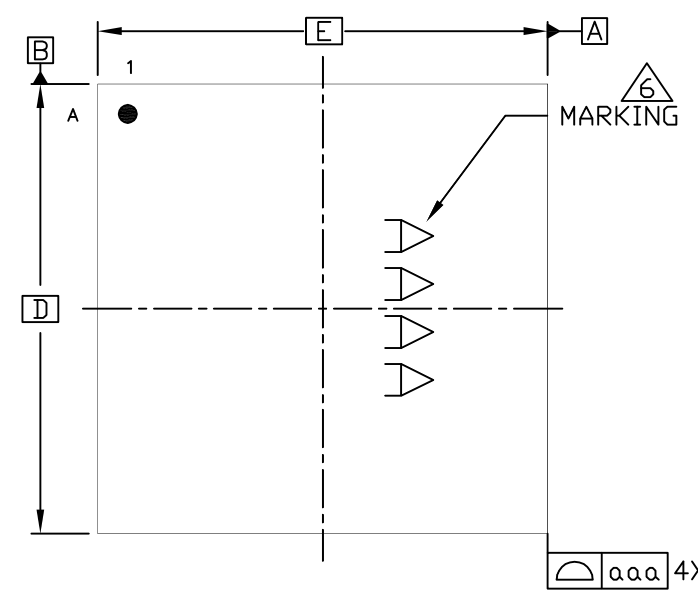
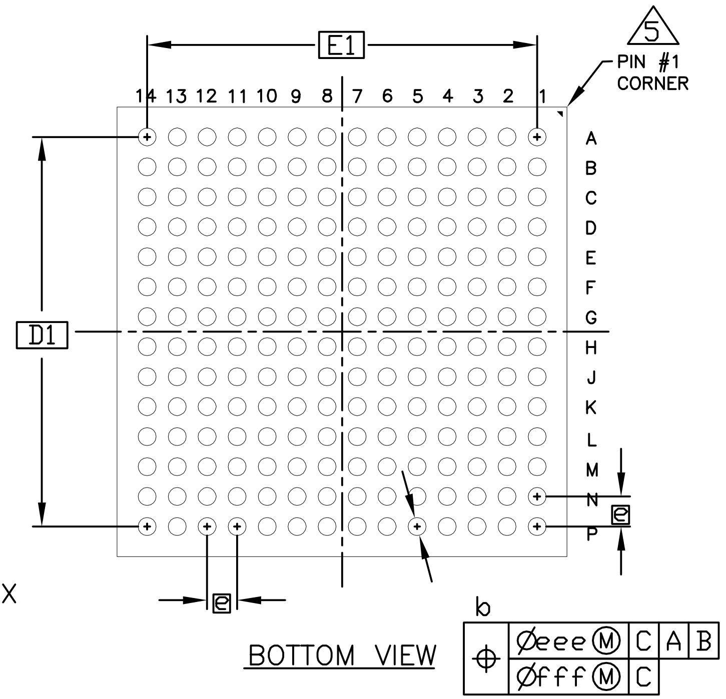
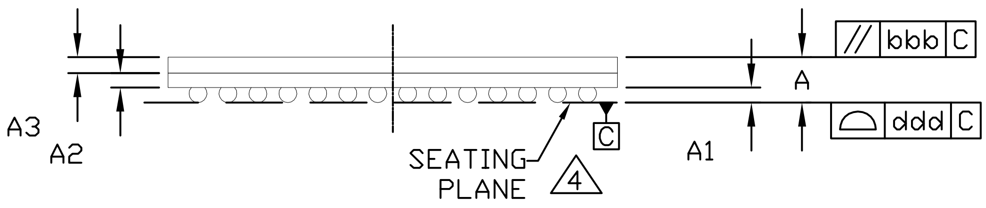


TOP VIEW



BOTTOM VIEW



SIDE VIEW

DIMENSIONS			
REF.	MIN.	NOM.	MAX.
A	1.402	1.512	1.622
A1	0.400	–	0.600
A2	0.482 REF		
A3	0.530 REF		
D	15.000 BSC		
D1	13.000 BSC		
E	15.000 BSC		
E1	13.000 BSC		
b	0.500	–	0.700
e	1.00 BSC		
aaa	0.200		
bbb	0.250		
ddd	0.200		
eee	0.250		
fff	0.100		
N	196		

NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. MATERIAL MUST COMPLY WITH BANNED AND RESTRICTED SUBSTANCES SPEC #10-0131.
3. THE BASIC SOLDER BALL GRID PITCH IS 1.00 MM AND BALL DIA IS 0.600 MM.
4. PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. A1 BALL PAD CORNER I.D.
6. MARKING SHOWN IS FOR PKG. ORIENTATION ONLY.
7. ALL DIMENSIONS APPLY TO LEADFREE (+) PKG. CODES ONLY.
8. THIS IS A CUSTOM PACKAGES
9. PACKAGE CODE: X19655FM+2

–DRAWING NOT TO SCALE–

maxim integrated™

TITLE:
PACKAGE OUTLINE, 196 BALLS
FLIP CHIP BGA, 15x15x1.512mm

APPROVAL	DOCUMENT CONTROL NO.	REV.	
EDEN CHEN 10/14/13	21-0679	C	1/1